Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6395	(dic$3 near5 (tape film substrate))	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 18:27
L2	5420	1 and (trench groove recess via open$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 18:28
L3	3600	2 and (insulat$3 encapsulat$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 18:28
L5	3600	3 and ((insulat$3 encapsulat$3) nea100 (dic$3 near5 (tape film substrate)))	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 18:06
L6	204	5 and stretch$3	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 18:07
L7	2900	(dic$3 near5 (tape film substrate))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 18:27
L8	671	7 and (trench groove recess via open$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 18:28
L9	141	8 and (insulat$3 encapsulat$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 18:28

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L21	666	(mold$3 same encapsulat$3 same (barrier protect$3) same (peel$3 remov$3))	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 20:48
L22	190	(mold$3 same encapsulat$3 same (barrier protect$3) same (peel$3 remov$3) same (groove recess open$3 trench$3))	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 20:50
L23	282	((mold$3 resin) same encapsulat$3 same (barrier protect$3) same (peel$3 remov$3) same (groove recess open$3 trench$3))	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 20:50
L24	282	22 23	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 20:51